Product Change Notification / LIAL-16UCZH910

Date:

22-Sep-2021

Product Category:

Linear Op Amps

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4732 Final Notice: Qualification of MMT as an additional assembly site for selected MCP6031, MCP6033, MCP6002, MCP6231 and MCP6241 device families available in 8L DFN (2x3x0.9mm) package.

Affected CPNs:

LIAL-16UCZH910_Affected_CPN_09222021.pdf
LIAL-16UCZH910_Affected_CPN_09222021.csv

Notification Text:

PCN Status:
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open one of the files found in the Affected CPNs section

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of MMT as an additional assembly site for selected MCP6031, MCP6033, MCP6002, MCP6231 and MCP6241 device families available in 8L DFN (2x3x0.9mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	UTAC Thai Limited (NSEB)	UTAC Thai Limited (NSEB)	Microchip Technology Thailand (Branch) (MMT)
Wire material	Au	Au	CuPdAu
Die attach material	8600	8600	3280
Molding compound material	G700LTD	G700LTD	G700LTD
Lead frame material	EFTEC-64T	EFTEC-64T	C194
DAP Surface Prep	Ag	Ag	Bare Cu
Lead frame plating finish	Matte Tin	Matte Tin	Matte Tin
Lead frame lead-lock	No	No	Yes
	See Pre and Post Change attachment for lead frame comparison		

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date: October 01, 2021 (date code: 2140)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Due to unforeseen circumstances, that are out of Microchip's control, full qualification will be made available as soon as it is approved which may be after the estimated first ship date so that Microchip can maintain continuity of supply and not disrupt customer orders.

Time Table Summary:

	June 2021					**-->**	**September 2021**				**October 2021**				
Workweek	23	24	25	26	27		36	37	38	39	40	41	42	43	44
Initial PCN Issue Date				X											
Final PCN Issue Date									X						
Qual Report Availability															X
Estimated Implementation Date											X				

Method to Identify Change:

Traceability code

Estimated Qualification Completion Date:

October 2021

Note 1: This final PCN will be updated to include the Qualification report as soon as it is completed.

Note 2: Please be advised the qualification completion times may be extended because of unforeseen business conditions.

Revision History:

June 21, 2021: Issued initial notification.**September 22, 2021**: Issued final notification. Provided estimated first ship date to be October 01, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-16UCZH910_Pre and Post Change Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

CCB 4732
Pre and Post Change Summary
PCN#: LIAL-16UCZH910

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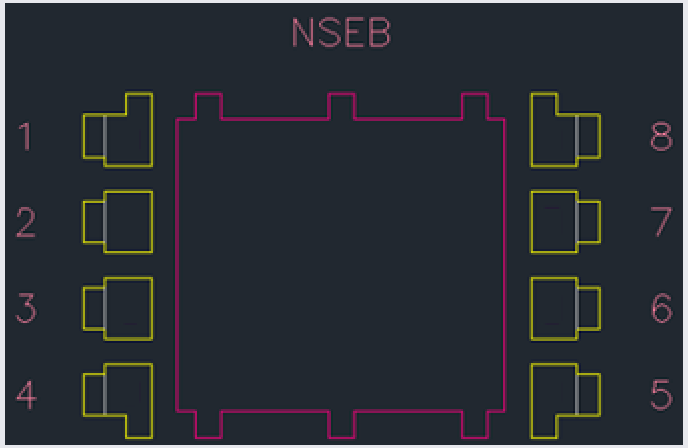
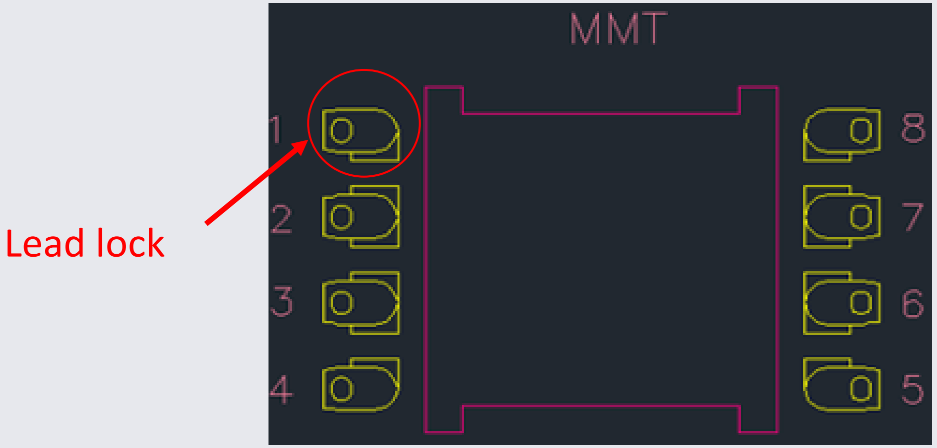
Lead frame comparison

Pre Change	Post change
NSEB	**MMT**



Lead frame material	EFTEC-64T
Lead frame DAP surface prep	Ag
Lead frame lead-lock	No


Lead lock

Lead frame material	C194
Lead frame DAP surface prep	Bare Cu
Lead frame lead-lock	Yes

NOTE: Mold compound material fills the lead lock hole, which provides improved protection against moisture penetration along the edge of the leads (pins) of the package.

Affected Catalog Part Numbers (CPN)

MCP6031-E/MC
MCP6031T-E/MC
MCP6033-E/MC
MCP6033T-E/MC
MCP6002-E/MC
MCP6002T-E/MC
MCP6231-E/MC
MCP6231T-E/MC
MCP6241-E/MC
MCP6241T-E/MC
MCP6002-E/MCVAO
MCP6002T-E/MCVAO